## Evaluation of Performance for Enzymatic Biofuel Cells with Microelectrode Arrays Inside a Blood Artery Via Finite Element Approach

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## Abstract

Introduction

Enzymatic biofuel cells (EBFCs) are considered as a candidate for miniature implantable power sources, which use enzymes as catalysts to perform redox reaction with biological fuels such as glucose. In this study, the performance of an EBFC chip inside a blood artery, involving highly dense and three dimensional cylindrical microelectrode arrays has been simulated via finite element approach. Based on the our previous results on microelectrode arrays' design rule and orientation of chip in the blood artery, the main focus of this research is to investigate diffusion of glucose, output potential, current density and power density of the EBFC chip under the transient state condition.

Use of COMSOL Multiphysics®

In the model design, we applied the 1) Michaelis Menten equation; 2) Nernst potential equation; 3) Navier Strokes velocity and 4) Fick's diffusion law to investigate the EBFC chip in the blood artery. Figure 1 is the geometry of one pair of anode and cathode immobilized with glucose oxidase (GOx) and laccase, respectively.

There are three models applied in this design:

1. Conductive media DC application model

Boundary Condition Enzyme layer interface layer Insulation Enzyme layers - bulk interface Continuity Top boundary of outer bulk domain Inward flux Bottom boundary of outer bulk domain Convective flux SiO2 boundary Insulation

2. Electro-kinetic application model

Boundary Condition Enzyme layer interface Continuity Enzyme layers - bulk interface Nernst potential expressions Outer bulk Insulation/Symmetry SiO2 layer Insulation

3. Incompressible Navier-Stokes application model

Boundary Condition Enzyme layer interface Wall - no slip Enzyme layers - bulk interface Continuity Top boundary of outer bulk domain Inlet pressure Bottom boundary of outer bulk domain Outlet - No viscous stress SiO2 layer Insulation

## Figures used in the abstract



Figure 1: Schematic of EBFC.